

You are in: Business | Business

SIGN UP TO

- [Email Newsletters](#)
- [RSS Feeds](#)
- [Digital Magazine](#)
- [Print Magazine](#)
- [Technical Papers](#)
- [Events](#)
- [Media Centre](#)

WORK BREAK

- [Photo Stories](#)
- [Blogs](#)
- [Video](#)
- [Sudoku](#)
- [Dilbert](#)
- [Gadget Master](#)
- [Made By Monkeys](#)

SEMICON Europa: Discrepancies in 450mm timing

David Manners
Tuesday 11 October 2011 16:58

450mm manufacturing will not be introduced until 2018 "or thereabouts", said Rob Hartmann of the world's No.1 lithography equipment manufacturer, ASML, which will come as a disappointment to TSMC which [says it will have a 450mm pilot line in 2013-14](#) and a volume production fab running 450mm wafers in 2015-16.

Hartmann made his statement in a panel session today at [Semicon Europa](#). The TSMC statement was made last week at IEF2011 in Seville.

Asked by Electronics Weekly how he felt about not having a tool ready to meet the TSMC timeline, Hartmann replied: "Ask TSMC if they are prepared to fund the development of the tool," adding: "I really wonder if they'll meet that timeline."

Asked if the \$4.4bn investment in 450mm at the College of Nanotechnology at Albany by the State of New York, Samsung, TSMC, Intel, IBM and Globalfoundries meant that Europe is too late to engage in a 450mm project, Hartmann replied: "That depends on European technology."

Hartmann added that he thought the EU would act if it was becoming clear that Europe was becoming uncompetitive.

Jean-Marc Chery, executive vp at ST, thought that it was more important to decide on whether to go down the finfet route or a device based on fully depleted SOI, before a decision on 450mm needed to be taken.

David Manners, Dresden

Like 2 people liked this.

Add New Comment

Login



Type your comment here.

Showing 0 comments

Sort by popular now

[M](#) [Subscribe by email](#) [S](#) [RSS](#)

Reactions



Comments powered by DISQUS

Related Articles

[SEMICON Europa: Fabs too costly for one country - SEMI](#)
11 Oct 2011

[SEMICON Europa: Plastic electronics should follow ARM's way - Saxby](#)
11 Oct 2011

[SEMICON Europa: Nanoelectronics needs clusters, says ST](#)
11 Oct 2011

[SEMICON Europa: EVG and Fraunhofer to develop 3D IC processes](#)
11 Oct 2011

[View all news](#)

Latest Blog posts

[Unconnected Among The Connected](#)
13 Oct 2011

[Arrow works with Freescale and Altera for Ethernet Powerlink](#)
12 Oct 2011

[Artificial Blood Vessels Made By Printer](#)
12 Oct 2011

[RoHS Recast CE - important to note](#)
12 Oct 2011

[View all blogs](#)

Share the content

[ShareThis](#)

Related Jobs

Most Viewed

[SEMICON Europa: Discrepancies in 450mm timing](#)

Posted: 16:58 11 Oct 2011

[IEF2011: HP to replace flash and SSD in 2013](#)

Posted: 12:17 06 Oct 2011

[Honeywell gets ovation from FAA, major movie studios - NBAA](#)

Posted: 09:50 10 Oct 2011

[Freescale unveils 'most powerful' automotive MCU](#)

Posted: 16:38 12 Oct 2011

[RF Micro Devices targets \\$1.5bn market with new business](#)

Posted: 17:02 12 Oct 2011

Products



» MAIN INDEX

» Acal

» Anglia

» Arrow Electronics

» Avnet Memec

» Avnet Silica

» Digi Key

» EBV Elektronik

» Farnell

» Future

» Mouser

» MSC Gleichmann UK

» RS



Read The Magazine

Latest Issue: 12 - 18 Oct, 2011

Sign-up for the ElectronicsWeekly.com newsletters:

